Special Issue

Selected papers from the APMM 2019–Active Polymeric Materials and Microsystems Conference

Message from the Guest Editors

This Special Issue will publish selected papers from the APMM 2019 – Active Polymeric Materials and Microsystems Conference, 16–19 September, 2019, in Dresden, Germany. The conference is co-organized by Technische Universität Dresden, Germany, and IPF – The Leibniz Institute of Polymer Research Dresden, Germany. Relevant topics include:

- Electro-active materials;
- Smart gels;
- Hydrogels and microgels;
- Synthesis and characterization, material properties;
- Responsive and adaptive systems;
- Hydrogel-based sensors, actuators, devices, and microsystems;
- Soft robots;
- Microfluidics;
- System integration, additive manufacturing;
- Modelling and simulation.

Guest Editors

Prof. Dr. Gerald Gerlach

Prof. Dr. Andreas Fery

Prof. Dr. Andreas Richter

Prof. Dr. Brigitte Voit

Prof. Dr. Thomas Wallmersperger

Deadline for manuscript submissions

closed (29 February 2020)

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